COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS: Q01

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01486</th>
<th>REV #: E1</th>
<th>SUN REV #: Not In VersionControl</th>
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<tr>
<td>TID #: TIDA-01486</td>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED: 5/14/2018 1:44:42 PM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
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